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Notice of Allowance: September 20, 2004

PATENT

Docket No. MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**RECEIVED
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Applicant : Lee, Teck Kheng
 Serial No. : 10/050,507
 Filing Date : January 16, 2002
 For: Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
 Group Art Unit: 2813
 Confirmation No.: 7687
 Examiner : THOMPSON, Craig

SEP 27 2004

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10
 I hereby certify that, on the date shown below, this correspondence is being transmitted by facsimile to Fax No.
 (703) 872-9306 addressed to Examiner Craig Thompson at the U.S. Patent and Trademark Office.

Date: 9-27-04*Patricia Rickure*

Mail Stop ISSUE FEE
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

COMMUNICATION

Sir:

Enclosed herewith is a copy of the following documents that were earlier submitted to the Examiner:

- Information Disclosure Statement/Form 1449 submitted by first class mail on September 9, 2004 with PTO-stamped return postcard.
- Information Disclosure Statement/Form 1449 submitted by facsimile on September 20, 2004 with Auto-Reply Facsimile Transmission. The PAIR records indicate that this IDS/Form 1449 was entered for this application.

The Examiner is requested to acknowledge receipt of the above documents, and return an initialed copy of each of the Forms 1449 to Applicant.

Respectfully submitted,

Kristine M. Strodthoff
 Kristine M. Strodthoff
 Reg. No. 34,259

Dated: September 27, 2004

WHYTE HIRSCHBOECK DUDEK S.C.
 555 East Wells Street, Suite 1900
 Milwaukee, Wisconsin 53202-3819
 (414) 273-2100
 Customer No. 31870

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THE STAMP OF THE U.S. PATENT OFFICE HEREON DENOTES RECEIPT
ON THE DATE STAMPED OF:

In re Application of : Lee, Teck Kheng
Serial No. : 10/050,507
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Poly Chip on
Flex for Die Stacking
Atty. Docket No. : MTI-31607

IIDS Transmittal

Enclosures: IIDS Transmittal; PTO-1449; twenty-two (22) references and return postcard.

DATE MAILED: September 9, 2004
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USPTO 9/20/2004 10:33 AM PAGE 1/001 FAX SERV^O
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W. M. B.

201

Patent

Attorney Docket No.: MIL-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
 Serial No. : 10/050,507
 Confirmation No. : 7687
 Filing Date : January 16, 2002
 For : Elimination of PDL Using Tape Base Flip Chip on Flex for Die
 Stocking
 Group Art Unit : 2812

DISCUSSION UNDER 37 C.F.R. §§ 1.56(a) and 1.56

I hereby certify that, on the date shown below, the correspondence below is being:

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Date: 9-30-04 Patricia Raye Dickin

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97/01

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. § 1.56, based on the attached Form PTO-1449 are those patent and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that there references be made of record in the present application, and that an initialled copy of the attached Form PTO-1449 be returned to the undersigned in accordance with 37CFR 502.

Respectfully submitted,

Kristine M. Stremmel
 Kristine M. Stremmel, Reg. No. 34259

Dated: September 20, 2004

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1 of 1

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Patent

Attorney Docket No.: MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
 Serial No. : 10/050,507
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 For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
 Group Art Unit : 2812

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

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INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached Form PTO-1449 are those patents and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that these references be made of record in the present application, and that an initialed copy of the attached Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.

Respectfully submitted,

Kristine M. Strodthoff, Reg. No. 34259

Dated: September 9, 2004

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MKE/748404.1

Patent

Attorney Docket No. MTI-31607

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| U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 | | ATTY. DOCKET NO. MTI-31607 | Serial No. 10/050,507 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Applicant Teck Kheng Lee | Confirmation No. 7687 |
| | | Filing Date January 16, 2002 | Group Art Unit 2813 |

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

| Examiner Initial | | Document Number | Publication Date | Country | Int'l Class | Sub-Class | Translation (Yes/No) |
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| | A3 | 99/65282 | 12-16-99 | WO | H05K | 1/11 | N/A |

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| Examiner Initials | Date Considered |
| EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | |

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1 of 2

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Patent

Attorney Docket No. MTI-31607

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| <p>U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> | ATTY. DOCKET NO. MTI-31607 <hr/> Applicant Teck Kheng Lee <hr/> Filing Date January 16, 2002 | Serial No. 10/050,507 <hr/> Confirmation No. 7687 <hr/> Group Art Unit 2813 |
|--|---|--|

| Examiner Initial | Non-Patent Document |
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Patent

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 Group Art Unit : 2812

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37 CFR 1.10

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Date: 4-20-04, 2004

Patricia Page Pickan

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached Form PTO-1449 are those patents and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

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Respectfully submitted,

Kristine M. Strodthoff
 Kristine M. Strodthoff, Reg. No. 34259

Dated: September 20, 2004

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Customer No.: 31870

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ATTY INITIALS _____ 1 of 1

Patent

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| U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 | ATTY. DOCKET NO. MTI-31607 | Serial No. 10/050,507 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | Applicant Teck Kheng Lee | Confirmation No. 7687 |
| | Filing Date January 16, 2002 | Group Art Unit 2813 |

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| Examiner Initial | Document No. | Publication/ Issue Date | Patentee | U.S. Class | Sub- Class |
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| Examiner Initials | Date Considered |
| EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | |

Patent

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| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Applicant Teck Kheng Lee | Confirmation No. 7687 |
| | | Filing Date January 16, 2002 | Group Art Unit 2813 |

| Examiner Initial | Document No. | Publication/ Issue Date | Patentee | U.S. Class | Sub-Class |
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| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | Applicant Teck Kheng Lee | Confirmation No. 7687 |
| | Filing Date January 16, 2002 | Group Art Unit 2813 |

| Examiner Initial | Document No. | Publication/ Issue Date | Patentee | U.S. Class | Sub-Class |
|------------------|--------------|----------------------------|------------------|------------|-----------|
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| A106 | 6,492,737 B1 | 12/2002 | Imasu et al. | | |

Examiner Initials

Date Considered

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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| U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 | | ATTY. DOCKET NO. MTI-31607 | Serial No. 10/050,507 |
| | | Applicant Teck Kheng Lee | Confirmation No. 7687 |
| | | Filing Date January 16, 2002 | Group Art Unit 2813 |

| Examiner Initial | Document No. | Publication/ Issue Date | Patentee | U.S. Class | Sub-Class |
|------------------|-----------------|----------------------------|-------------------|------------|-----------|
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